

LF2013
No Clean Liquid Flux

Product Description

Hasaconi lead-free soldering flux LF2013 is a no clean RMA type of liquid flux, which is specially developed in conjunction with the lead free solders. LF2013 is formulated based on an organic activator system to promote superior wetting performance and yet maintain a long-term electrical reliability. The flux leaves minimal colorless, dried and non-conductive assemblies after soldering, therefore post-soldering cleaning is not necessary.

Application

LF2013 is specially formulated for foaming, spraying and dipping processes. On board pre-heat temperature is recommended to be 90 – 110 °C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, LF2013 can be stored for up to 6 months. LF2013 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Pale yellow
Specific Gravity @ 25°C	0.828 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content (110°C, 1hr)	17.0 +/- 1.0 wt%
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	0.08 +/- 0.01 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test	48.0 +/- 5.0 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
IPC-TM-650 2.6.3.3	
JIS Z 3197 8.5.3	> 1 x 10 ¹¹ Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "M", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROM1
IPC J-STD-004	
Spread Factor	> 70% (Viromet 349)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Shinny

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